



CALL FOR PAPERS

Introduction

In the era of the Fourth Industrial Revolution, the convergence of traditional engineering and advanced digital technology has become a vital driver for sustainable development. Among these, Construction, Electronics, and Information Technology (IT) stand out as three foundational pillars driving modern economic and infrastructural growth. However, operating these sectors in silos often limits resource optimization and impedes comprehensive development.

Therefore, bridging and integrating these three fields through "Smart Systems" is an inevitable evolutionary step. Smart systems—powered by the Internet of Things (IoT), Artificial Intelligence (AI), Big Data, and automation—act as the core infrastructure that seamlessly connects physical construction structures with hardware electronics and software intelligence. This integration not only optimizes operations and reduces costs but also fosters breakthrough innovations such as smart cities, green buildings, and intelligent manufacturing.

This topic focuses on exploring technological solutions, architectural frameworks, and practical applications that enable the seamless connection between Construction, Electronics, and IT. By analyzing current trends and challenges, it aims to establish a collaborative ecosystem, unlocking new potentials for multi-industry development in the digital age.

Conference theme

Connecting Construction, Electronics, and IT through Smart Systems

Organizer

Tay Do University, Can Tho City, Vietnam

Duration and venue

Duration: 15 December, 2026

Venue: Tay Do University, Can Tho City, Vietnam

Important dates

Title submission deadline: August 31, 2026

Title acceptance notification: September 6, 2026

Abstract submission deadline: September 15, 2026

Full paper submission deadline: September 30, 2026

Full paper acceptance notification: October 25, 2026

Author registration and fee payment: October 30, 2026

Conference date: December 15, 2026.

Publication

Papers submitted to the conference will be evaluated by experts. Accepted papers will be published in the international conference proceedings with an ISBN.

Participation and publication fees

Non-Vietnamese participants

Conference participation fee: US\$20 (US\$30 if paid after October 30, 2026). Students pay US\$10. Presenters are free.

Publication fee: US\$50.

Vietnamese participants

Conference participation fee: VND 500,000 (VND 750,000 if paid after October 30, 2026). Students pay VND 200,000. Presenters are free.

Publication fee: VND 1,000,000.

Payment details

Account name: Tay Do University

Account number: 6815686868

Bank: ACB, Can Tho City

Payment Description: [Author's Name]-HTQT-TDU2026, Citizen Identity Card

The topics of the conference include, but are not limited to the following:

AI-Driven Analytics and Cloud Platforms for Smart Building Lifecycle Management

Integrating Edge Computing and IoT for Real-Time Structural Health Monitoring

Big Data Analytics in Construction and Electronics: Optimizing Operations through Smart Systems

Building Information Modeling (BIM) Integrated with IoT and Cloud Databases

Cybersecurity and Data Privacy in IT-Enabled Smart Infrastructure Systems

Blockchain Technology for Secure Data Exchange and Supply Chain Management in Smart Construction

Designing Middleware and Software Platforms for Electronic-Construction System Convergence.

Smart Building Management Systems (BMS): Integrating IoT and IT for Energy Efficiency

Digital Twins in Construction: Connecting Physical Structures with Electronic Sensors and Cloud Computing

Smart Materials and Embedded Electronics for Structural Health Monitoring (SHM)

Developing Intelligent Transportation Systems (ITS) through the Synergy of Infrastructure, Electronics, and AI

Applied IoT and GIS (Geographic Information Systems) for Real-time Smart Construction Site Management

Green Construction and Eco-friendly Electronics: Driving Sustainable Development through Smart Data

Contact

Authors are kindly requested to submit their papers via email. To facilitate the review and registration process, please include the following details in the body of your email or on the cover page of your manuscript:

Paper Title, Author Name(s), Affiliation / Institutional Address, Email Address, Phone Number

Submission Email: icset@tdu.edu.vn

Email Subject Line: icset – 2026, [Primary Author Name] - [Paper Title]

Chairman of Organizing Committee



Prof. Dr. Tran Cong Luan

Abstract template

Guidelines for paper submission

Authors are recommended to follow the format below.

Abstract template

Title: A title with the first word and proper nouns capitalized.

< Centered bold, Time New Roman 14, Single space >

Authors: Full names (given name, middle initial, family name) of all authors.

< Centered bold, Time New Roman 12, Single space >

Institutions: Institution name, province/state, and country. The institutions of the authors with location denoted with a number (1, 2, and 3) behind the author's last name.

< Centered italic, Time New Roman 12, Single space >

Corresponding authors: An email address of corresponding author

(Left, Time New Roman 12, Single space)

Abstract

< Left bold, Time New Roman 12, Single space >

Body of Abstract

An abstract with a single paragraph of no more than 300 words that should state important objectives, methods, results and principal conclusions of the study. Abbreviations are defined at first use.

< Justify, Time New Roman 12, Single space >

Keywords: List up to 5 words in alphabetical order and separated by a comma. Capitalize only proper nouns. Do NOT use abbreviations.

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